TOSHIBA MOS DIGITAL INTEGRATED CIRCUIT SILICON GATE CMOS

# 524,288 WORDS × 8 BIT STATIC RAM

## DESCRIPTION

The TC554001FI/FTI is a 4,194,304-bit static random access memory (SRAM) organized as 524,288 words by 8 bits. Fabricated using Toshiba's CMOS Silicon gate process technology, this device operates from a single 5V ± 10% power supply. Advanced circuit technology provides both high speed and low power at an operating current of 10mA/MHz(typ) and minimum cycle time of 85 ns.It is automatically placed in low-power mode at 140 μA standby current (max) when chip enable ($\overline{CE}$) is asserted high. There are two control inputs. $\overline{CE}$ is used to select the device and for data retention control, and output enable ($\overline{OE}$) provides fast memory access. This device is well suited to various microprocessor system applications where high speed, low power and battery backup are required.And, with a guaranteed operating range of -40 to 85℃, the TC554001FI/FTI can be used in environments exhibiting extreme temperature conditions. The TC554001FI/FTI is available in a standard plastic 32-pin small-outline package(SOP) and 32-pin thin-small-outline package(TSOP).

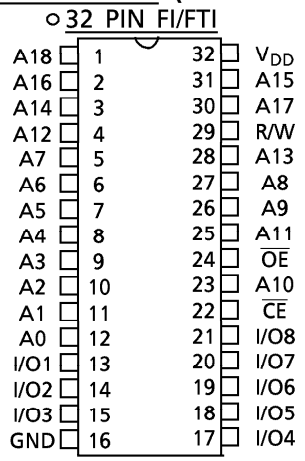
## FEATURES

- Low-power dissipation
  Operating: 55 mW/MHz (typical)
- Standby current of 8 μA (maximum) at Ta = 25°C
- Single power supply voltage of 5 V ± 10 %
- Power down features using $\overline{CE}$
- Data retention supply voltage of 2.0 to 5.5 V
- Directly TTL compatibility for all inputs and outputs
- Wide operating temperature range of – 40° to 85°C
- Access Time (maximum)

| | TC551001FI/FTI | |
|---|---|---|
| | -85L | -10L |
| Access Time | 85 ns | 100 ns |
| $\overline{CE}$ Access Time | 85 ns | 100 ns |
| OE Access Time | 45 ns | 50 ns |

- Package:
  SOP32-P-525-1.27 (FI) (Weight: 1.14 g typ)
  TSOP II 32-P-400-1.27 (FTI) (Weight: 0.51 g typ)

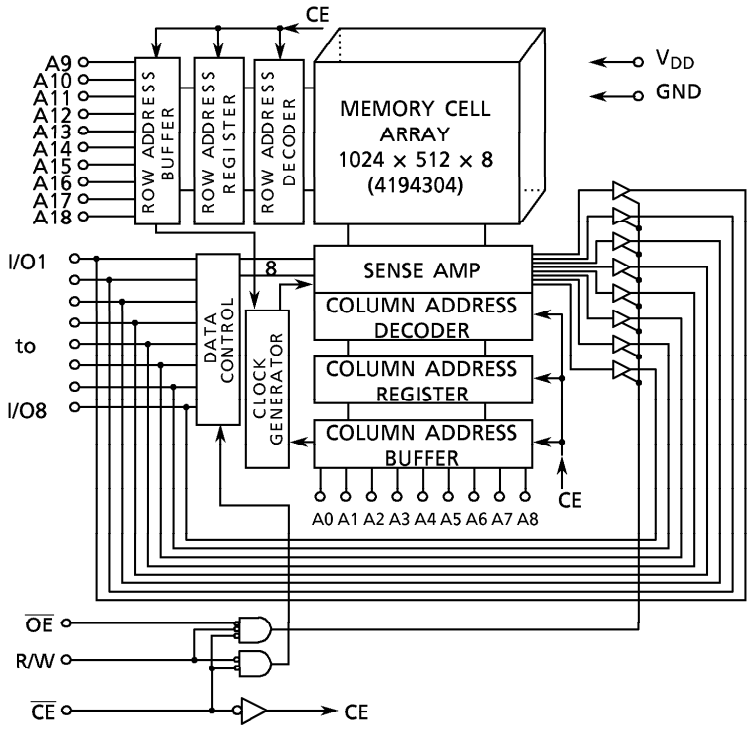
## PIN ASSIGNMENT (TOP VIEW)




## PIN NAMES

| | |
|---|---|
| A0 to A18 | Address Inputs |
| R/W | Read/Write Control |
| $\overline{OE}$ | Output Enable |
| $\overline{CE}$ | Chip Enable |
| I/O1 to I/O8 | Data Input/Output |
| $V_{DD}$ | Power ( + 5 V) |
| GND | Ground |

## BLOCK DIAGRAM

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## OPERATION MODE

| OPERATION MODE | $\overline{CE}$ | $\overline{OE}$ | R/W | I/O1 to I/O8 | POWER |
|---|---|---|---|---|---|
| Read | L | L | H | $D_{OUT}$ | $I_{DDO}$ |
| Write | L | × | L | $D_{IN}$ | $I_{DDO}$ |
| Output Disabled | L | H | H | High-Z | $I_{DDO}$ |
| Standby | H | × | × | High-Z | $I_{DDS}$ |

Note: × = don't care. H=logic high. L=logic low.

## ABSOLUTE MAXIMUM RATINGS

| SYMBOL | RATING | VALUE | UNIT |
|---|---|---|---|
| $V_{DD}$ | Power Supply Voltage | − 0.3 to 7.0 | V |
| $V_{IN}$ | Input Voltage | − 0.3* to 7.0 | V |
| $V_{I/O}$ | Input and Output Voltage | − 0.5 to $V_{DD}$ + 0.5 | V |
| $P_D$ | Power Dissipation | 0.6 | W |
| Tsolder | Soldering Temperature (10 s) | 260 | °C |
| Tstrg. | Storage Temperature | − 55 to 150 | °C |
| Topr. | Operating Temperature | − 40 to 85 | °C |

* − 3.0 V when measured at a pulse width of 50 ns

## DC RECOMMENDED OPERATING CONDITIONS (Ta = – 40° to 85°C)

| SYMBOL | PARAMETER | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{DD}$ | Power Supply Voltage | 4.5 | 5.0 | 5.5 | V |
| $V_{IH}$ | Input High Voltage | 2.4 | – | $V_{DD}$ + 0.3 | V |
| $V_{IL}$ | Input Low Voltage | – 0.3* | – | 0.6 | V |
| $V_{DH}$ | Data Retention Supply Voltage | 2.0 | – | 5.5 | V |

* – 3.0 V when measured at a pulse width of 50 ns

## DC CHARACTERISTICS (Ta = – 40° to 85°C, $V_{DD}$ = 5 V ± 10%)

| SYMBOL | PARAMETER | TEST CONDITION | | | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|---|---|
| $I_{IL}$ | Input Leakage Current | $V_{IN}$ = 0 V to $V_{DD}$ | | | – | – | ± 1.0 | μA |
| $I_{OH}$ | Output High Current | $V_{OH}$ = 2.4 V | | | – 1.0 | – | – | mA |
| $I_{OL}$ | Output Low Current | $V_{OL}$ = 0.4 V | | | 2.1 | – | – | mA |
| $I_{LO}$ | Output Leakage Current | $\overline{CE}$ = $V_{IH}$ or R/W = $V_{IL}$ or $\overline{OE}$ = $V_{IH}$<br>$V_{OUT}$ = 0 V to $V_{DD}$ | | | – | – | ± 1.0 | μA |
| $I_{DDO1}$ | Operating Current | $\overline{CE}$ = $V_{IL}$ and R/W = $V_{IH}$<br>$I_{OUT}$ = 0 mA<br>Other Inputs = $V_{IH}/V_{IL}$ | Tcycle | min | – | – | 80 | mA |
| | | | | 1 μs | – | 15 | – | |
| $I_{DDO2}$ | | $\overline{CE}$ = 0.2 V and R/W = $V_{DD}$ – 0.2 V<br>$I_{OUT}$ = 0 mA<br>Other Inputs = $V_{DD}$ – 0.2 V/0.2 V | Tcycle | min | – | – | 70 | mA |
| | | | | 1 μs | – | 10 | – | |
| $I_{DDS1}$ | Standby Current | $\overline{CE}$ = $V_{IH}$ | | | – | – | 3 | mA |
| $I_{DDS2}$ | | $\overline{CE}$ = $V_{DD}$ – 0.2 V<br>$V_{DD}$ = 2.0 to 5.5 V | Ta = 25°C | | – | 4 | 8 | μA |
| | | | Ta = – 40° to 85°C | | – | – | 140 | |

## CAPACITANCE (Ta = 25°C, f = 1 MHz)

| SYMBOL | PARAMETER | TEST CONDITION | MAX | UNIT |
|---|---|---|---|---|
| $C_{IN}$ | Input Capacitance | $V_{IN}$ = GND | 10 | pF |
| $C_{OUT}$ | Output Capacitance | $V_{OUT}$ = GND | 10 | pF |

Note: This parameter is periodically sampled and is not 100% tested.

## AC CHARACTERISTICS AND OPERATING CONDITIONS

(Ta = – 40° to 85°C, $V_{DD}$ = 5 V ± 10%)

### READ CYCLE

| SYMBOL | PARAMETER | TC554001FI/FTI | | | | UNIT |
|---|---|---|---|---|---|---|
| | | -85L | | -10L | | |
| | | MIN | MAX | MIN | MAX | |
| $t_{RC}$ | Read Cycle Time | 85 | – | 100 | – | ns |
| $t_{ACC}$ | Address Access Time | – | 85 | – | 100 | |
| $t_{CO}$ | Chip Enable Access Time | – | 85 | – | 100 | |
| $t_{OE}$ | Output Enable Access Time | – | 45 | – | 50 | |
| $t_{COE}$ | Chip Enable Low to Output in Active | 5 | – | 5 | – | |
| $t_{OEE}$ | Output Enable Low to Output Active | 0 | – | 0 | – | |
| $t_{OD}$ | Chip Enable Hige to Output High-Z | – | 35 | – | 40 | |
| $t_{ODO}$ | Output Enable Hige to Output High-Z | – | 35 | – | 40 | |
| $t_{OH}$ | Output Data Hold Time | 10 | – | 10 | – | |

### WRITE CYCLE

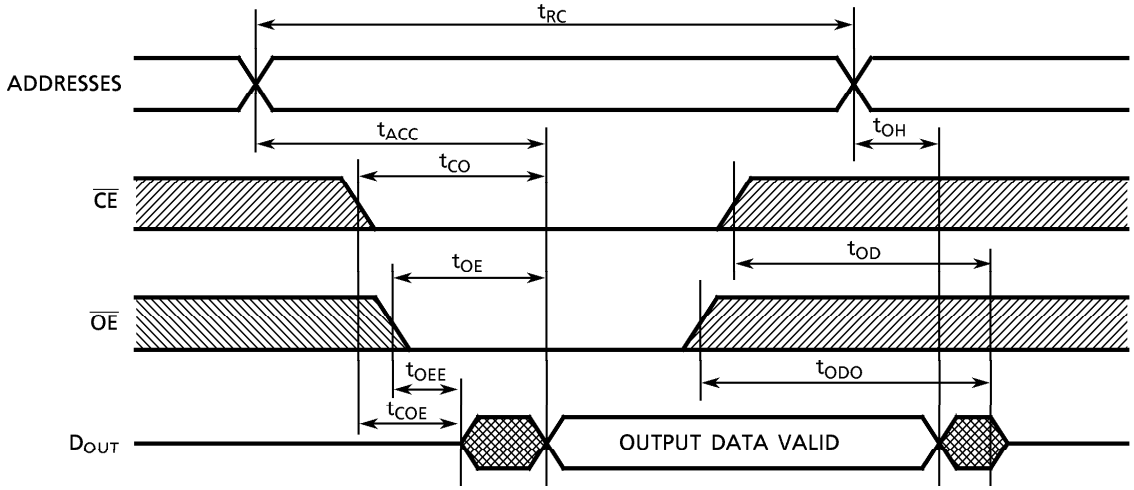
| SYMBOL | PARAMETER | TC554001FI/FTI | | | | UNIT |
|---|---|---|---|---|---|---|
| | | -85L | | -10L | | |
| | | MIN | MAX | MIN | MAX | |
| $t_{WC}$ | Write Cycle Time | 85 | – | 100 | – | ns |
| $t_{WP}$ | Write Pulse Width | 55 | – | 60 | – | |
| $t_{CW}$ | Chip Enable to End of Write | 70 | – | 80 | – | |
| $t_{AS}$ | Address Setup Time | 0 | – | 0 | – | |
| $t_{WR}$ | Write Recovery Time | 0 | – | 0 | – | |
| $t_{ODW}$ | R/W Low to Output High-Z | – | 35 | – | 40 | |
| $t_{OEW}$ | R/W High to Output Active | 0 | – | 0 | – | |
| $t_{DS}$ | Data Setup Time | 35 | – | 40 | – | |
| $t_{DH}$ | Data Hold Time | 0 | – | 0 | – | |

### AC TEST CONDITIONS

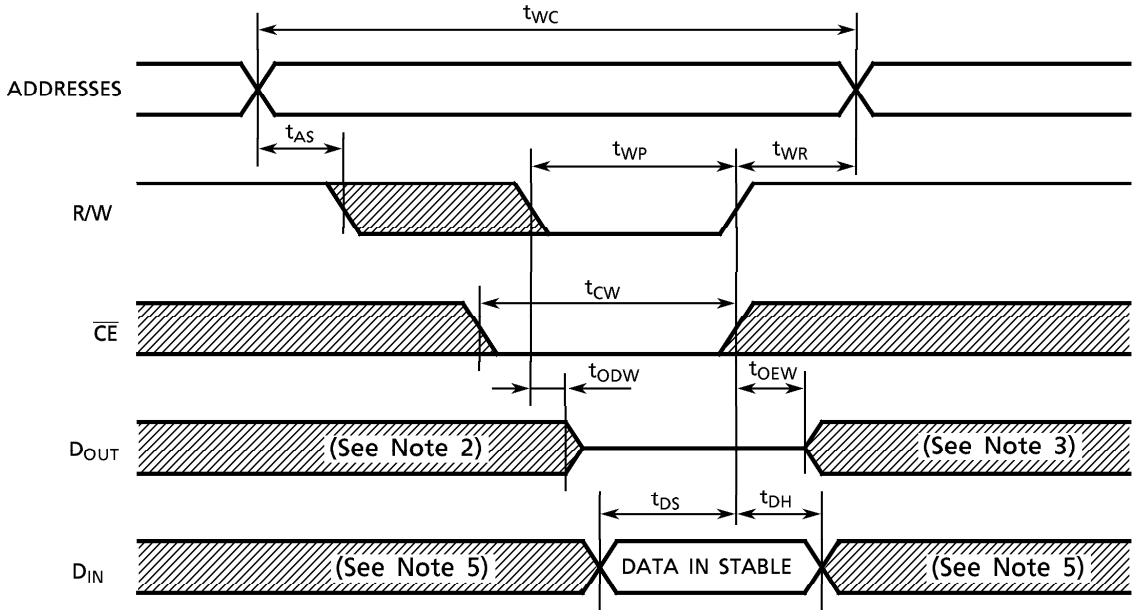
Output Load: 100 pF + one TTL gate
Input Pulse Level: 0.4 V, 2.6 V
Timing Measurements: 1.5 V
Reference Level: 1.5 V
$t_r$, $t_F$: 5 ns

## TIMING WAVEFORMS

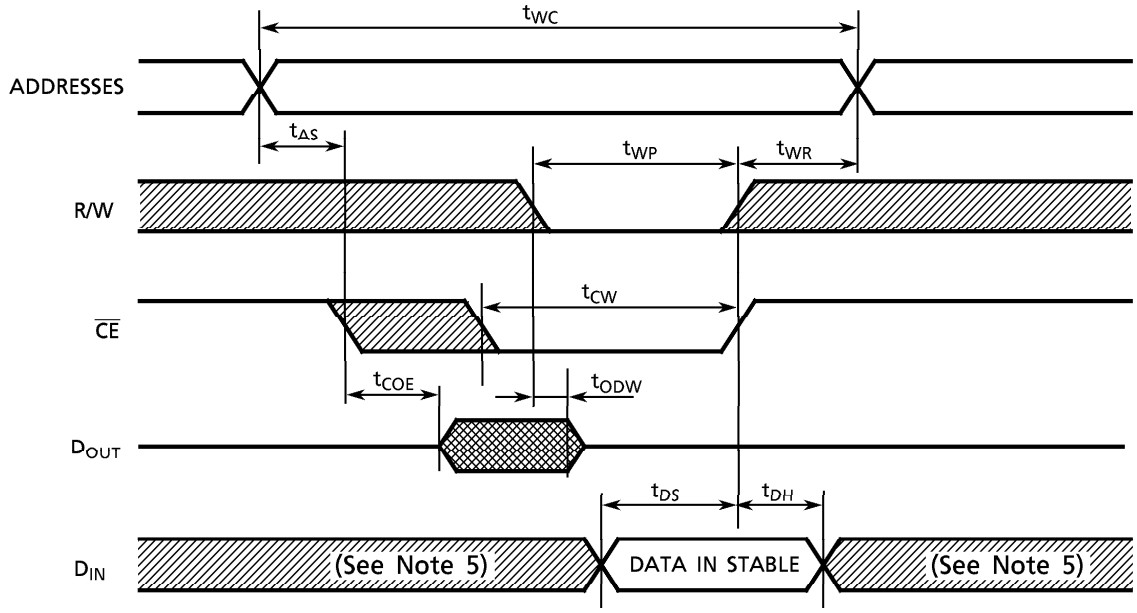
### READ CYCLE (See Note 1)




### WRITE CYCLE 1 (R/W CONTROLLED) (See Note 4)



WRITE CYCLE 2 ($\overline{CE}$ CONTROLLED) (See Note 4)




(1) R/W remains High for Read Cycle.

(2) If $\overline{CE}$ goes coincident with or after R/W goes LOW, the output will remain at high impedance.

(3) If $\overline{CE}$ goes HIGH coincident with or before R/W goes HIGH, the output will remain at high impedance.

(4) IF $\overline{CE}$ is HIGH during the write cycle, the outputs will remain at high impedance.

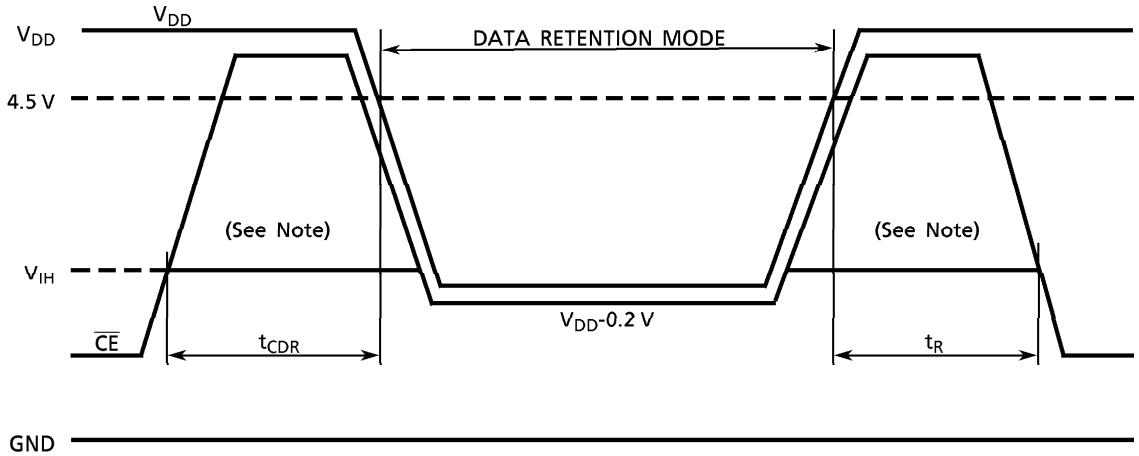
(5) Because I/O signals may be in the output state at this time, input signals of reverse polarity must not be applied.

## DATA RETENTION CHARACTERISTICS (Ta = – 40° to 85°C)

| SYMBOL | PARAMETER | | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|
| $V_{DH}$ | Data Retention Supply Voltage | | 2.0 | – | 5.5 | V |
| $I_{DDS2}$ | Standby Current | $V_{DH}$ = 3.0 V | – | – | 70 * | μA |
| | | $V_{DH}$ = 5.5 V | – | – | 140 | |
| $t_{CDR}$ | Chip Deselect to Data Retention Mode Time | | 0 | – | – | nS |
| $t_R$ | Recovery Time | | 5 | – | – | mS |

*) 6 μA (max) Ta = – 40° to 40°C

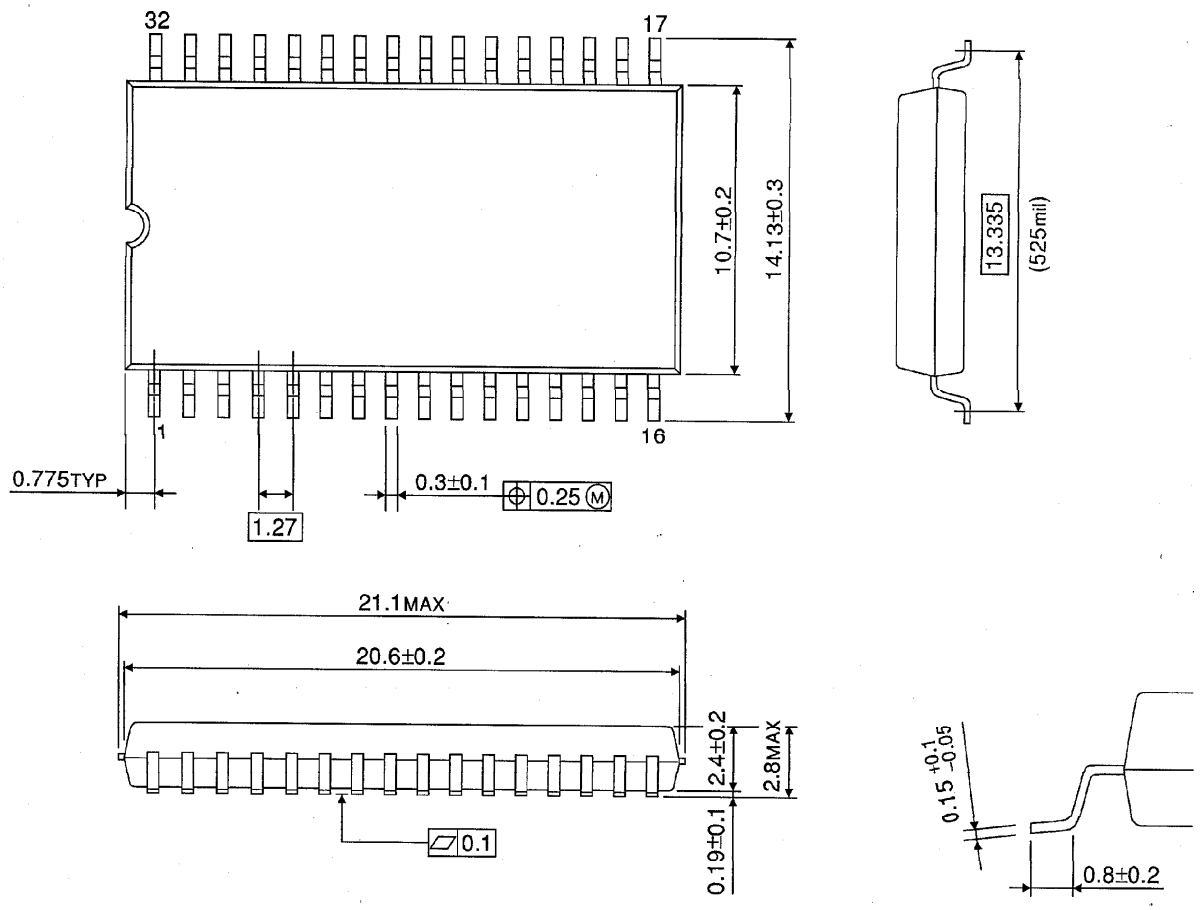
## $\overline{CE}$ Controlled Data Retention Mode




Note: When $\overline{CE}$ is operating at the $V_{IH}$ level (2.4V), the standby current is given by $I_{DDS1}$ during the transition of $V_{DD}$ from 4.5 to 2.6V.

PACKAGE DIMENSIONS (SOP32-P-525-1.27)

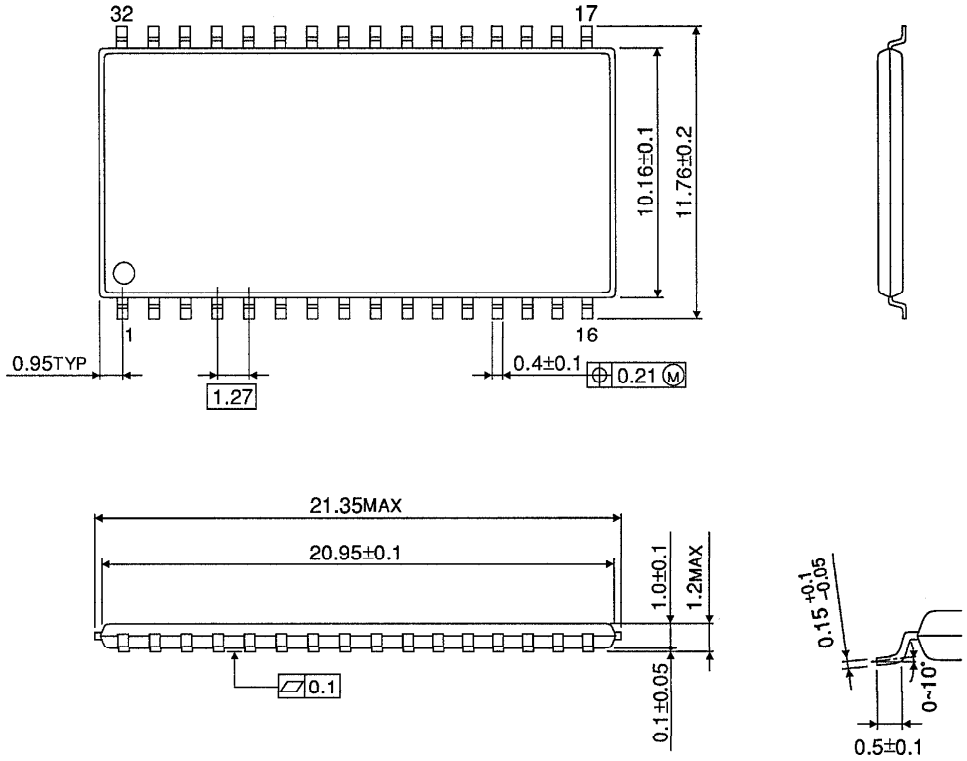
Unit in mm




Weight: 1.14 g (typ)

PACKAGE DIMENSIONS (TSOP II 32-P-400-1.27)

Unit in mm




Weight: 0.51 g (typ)